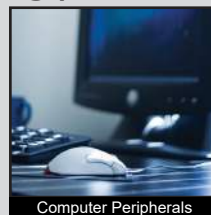
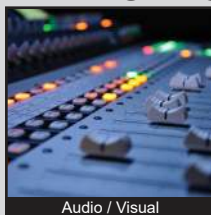


# TL6400 SERIES TACT SWITCH

ANTI-VANDAL SWITCHES  
 DETECTOR SWITCHES  
 DIP SWITCHES  
 KEYLOCK SWITCHES  
 NAVIGATION SWITCHES  
 PUSHBUTTON SWITCHES  
 ROCKER SWITCHES  
 ROTARY SWITCHES  
 SLIDE SWITCHES  
 SNAP ACTION SWITCHES  
**TACTILE SWITCHES**  
 TOGGLE SWITCHES  
 CAP OPTIONS



## APPLICATIONS / MARKETS



**RoHS**

## SPECIFICATIONS

**Electrical Rating:** 50mA, 12VDC  
**Contact Resistance:** 100mΩ Max. (Initial)  
**Insulation Resistance:** 100MΩ Min. at 100VDC  
**Dielectric Strength:** 250VAC for 1 Minute  
**Operating Temperature:** -40°C to 85°C  
**Storage Temperature:** -40°C to 85°C  
**Operating Force:** 160gf ± 50gf 50,000 cycles  
 260gf ± 70gf 30,000 cycles  
**Travel:** 0.15mm ± 0.10mm  
**Dust/Moisture Protection:** IP67  
**Function:** SPST, Off-(On)  
**Bounce:** 10msec Max.  
**Contact Material:** Silver  
**Packaging:** Actuator A: Tape and Reel, 1,800 pcs/reel  
 Actuator B: Tape and Reel, 1,500 pcs/reel

## FEATURES & BENEFITS

- Up to 50,000 cycle life expectancy
- Tape and Reel packaging
- Surface mount design
- Actuation force options
- IP67 rating for dust & moisture protection

## PART NUMBER CONFIGURATOR

Series	Circuit	Actuator	Force	Plating	Termination
<input type="text" value="TL"/>	<input type="text" value="6400"/>	<input type="text" value="A"/>	<input type="text" value="F160"/>	<input type="text" value="Q"/>	<input type="text" value="J"/>
		A - 4.30 B - 5.00	F160 - 160 gf - Black F260 - 260 gf - White	Q - Silver	J - J-bend

*Specifications subject to change without notice 4.15.2022*



**E-SWITCH®**

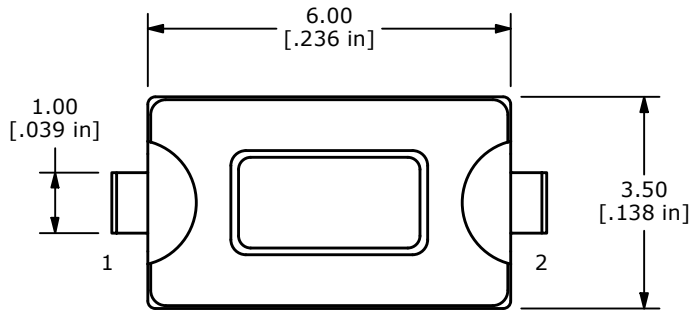
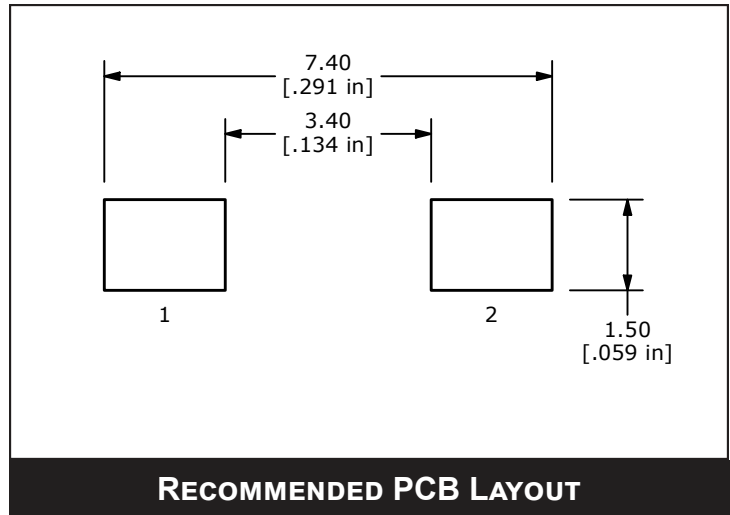
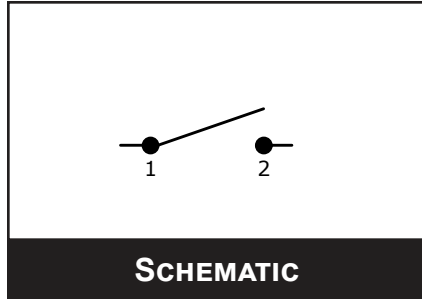
www.e-switch.com

800.867.2717

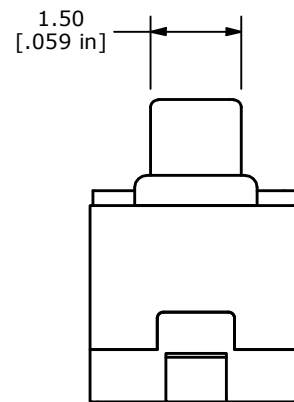
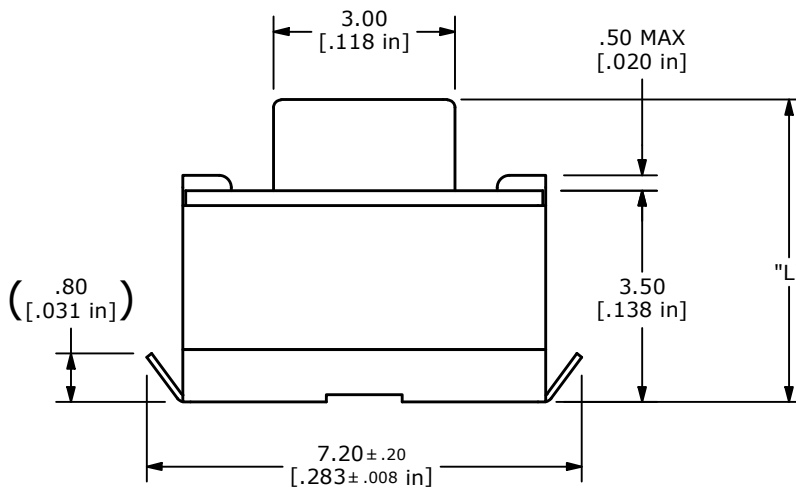
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# TL6400 SERIES TACT SWITCH

## BODY DIMENSIONS

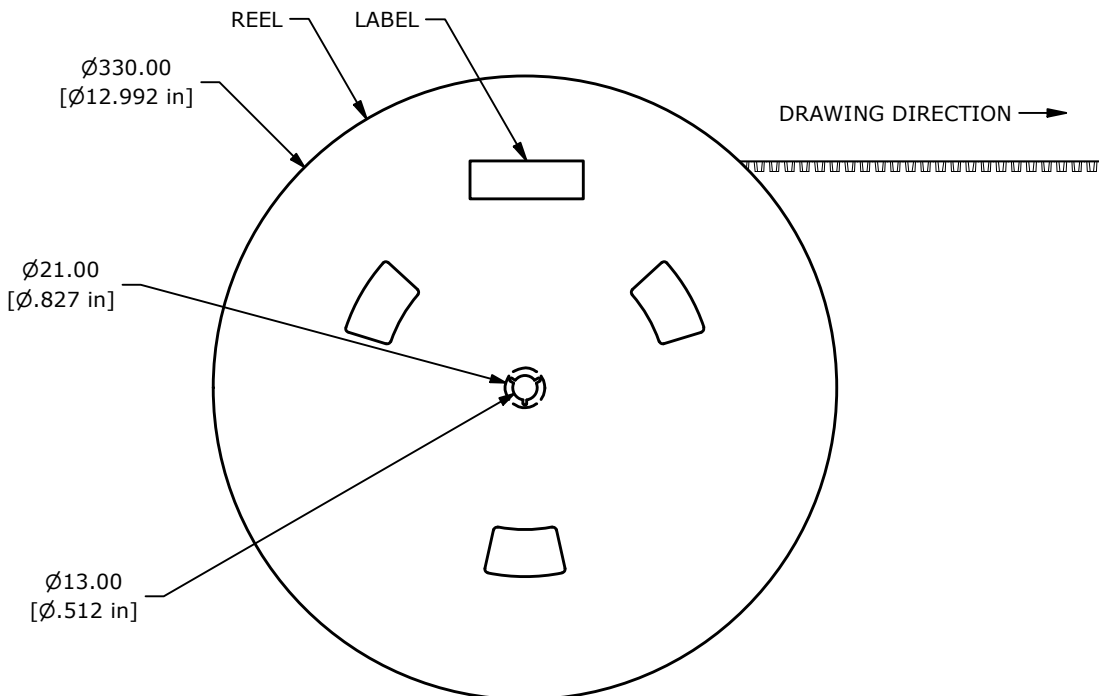
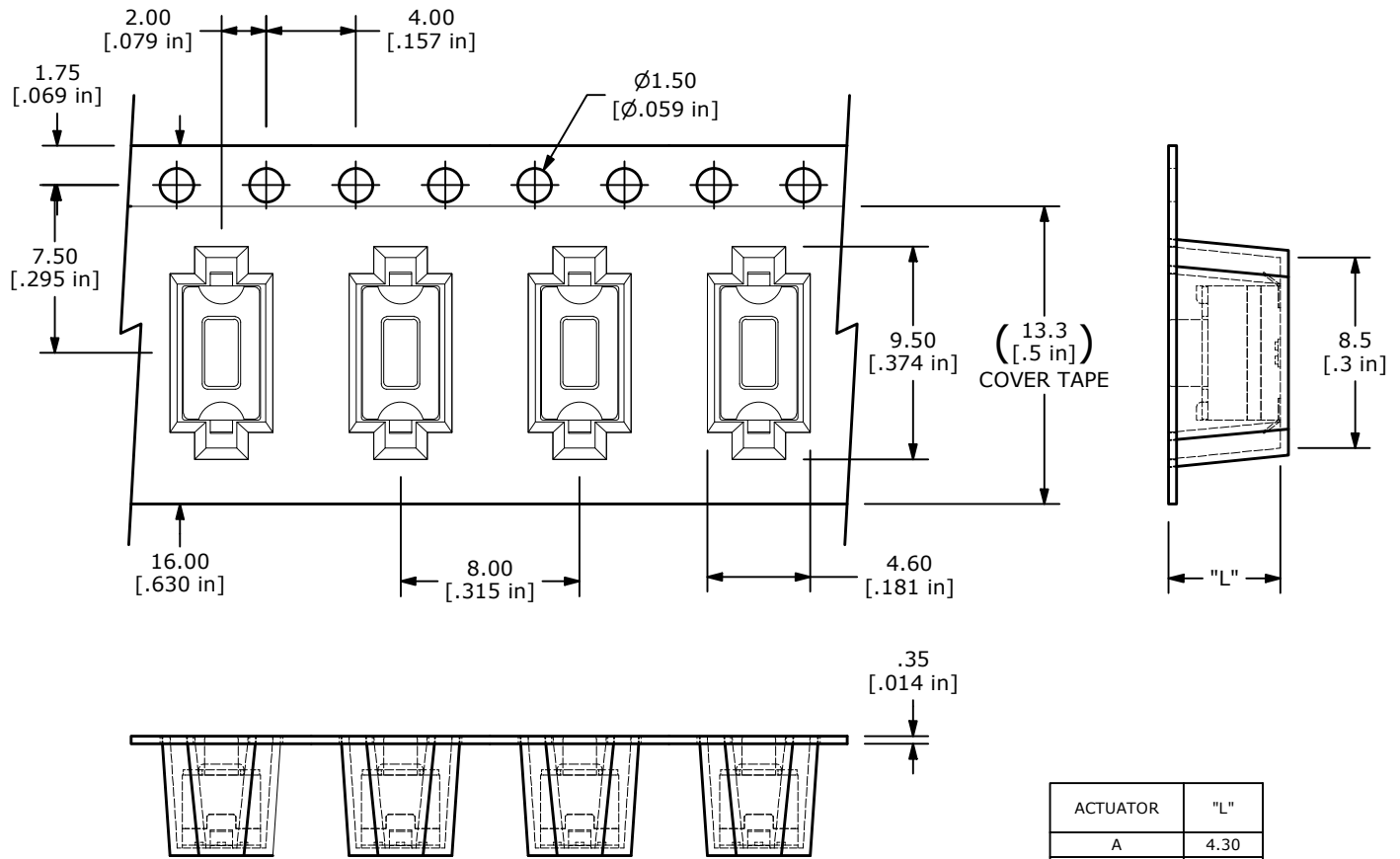


ACTUATOR	"L"
A	4.30
B	5.00



# TL6400 SERIES TACT SWITCH

## BODY DIMENSIONS TAPE AND REEL



# TL6400 SERIES TACT SWITCH

## RECOMMENDED SOLDER PROCESS

Most contamination problems can be prevented by exercising care during the cleaning and soldering process. Care should be taken not to immerse or spray unsealed switches during flux removal. Contact E-Switch for specific soldering recommendations and specifications not shown. Generalized soldering procedures are outlined below.

### “TYPICAL” SMT REFLOW (Pb and Pb-Free)

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate ( $T_{s_{max}}$ to $T_p$ )	3 °C/second max.	3 °C/second max.
<b>Preheat</b>		
-Temperature Min ( $T_{s_{min}}$ )	100 °C	150 °C
-Temperature Max ( $T_{s_{max}}$ )	150 °C	200 °C
-Time ( $t_{s_{min}}$ to $t_{s_{max}}$ )	60-120 seconds	60-180 seconds
Time Maintained above:		
-Temperature ( $T_L$ )	183 °C	217 °C
-Time ( $t_L$ )	60-150 seconds	60-150 seconds
Time within 5 °C of actual Peak Temperature ( $t_p$ )	10-30 seconds	20-40 seconds
Ramp-Down Rate	6 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature	6 minutes max.	8 minutes max.

*Note 1: All temperatures refer to topside of the package, measured on the package surface.*

